TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK2232

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4-V gate drive

• Low drain–source ON resistance : $RDS (ON) = 36 \text{ m}\Omega (typ.)$

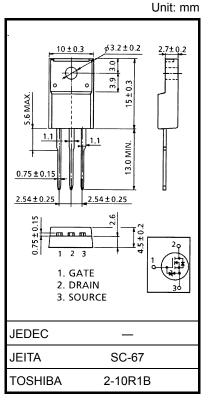
• High forward transfer admittance $: |Y_{fs}| = 16 S \text{ (typ.)}$

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 60 \text{ V)}$

• Enhancement mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit | |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 60 | V | |
| Drain-gate voltage (R _{GS} = 20 kΩ) | | V_{DGR} | 60 | V | |
| Gate-source voltage | | V _{GSS} | ±20 | V | |
| Drain current | DC (Note 1) | ΙD | 25 | Α | |
| | Pulse (Note 1) | I _{DP} | 100 | Α | |
| Drain power dissipatio | n (Tc = 25°C) | P_{D} | 35 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 156 | mJ | |
| Avalanche current | | I _{AR} | 25 | Α | |
| Repetitive avalanche energy (Note 3) | | E _{AR} | 3.5 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 3.57 | °C/W |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 62.5 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25 °C (initial), L = 339 μ H, R_{G} = 25 Ω , I_{AR} = 25 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device.

Please handle with caution.



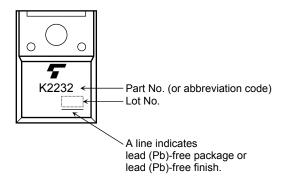
Electrical Characteristics (Ta = 25°C)

| Charac | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|---------------|----------------------|---|-----|-------|-------|------|
| Gate leakage cu | ırrent | I _{GSS} | V _{GS} = ±16 V, V _{DS} = 0 V | _ | _ | ±10 | μΑ |
| Drain cut-off cu | rrent | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V | _ | _ | 100 | μA |
| Drain-source br voltage | eakdown | V (BR) DSS | I _D = 10 mA, V _{GS} = 0 V | 60 | _ | _ | V |
| Gate threshold v | voltage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 0.8 | _ | 2.0 | V |
| Drain-source ON resistance | | Pro (OV) | V _{GS} = 4 V, I _D = 12 A | - | 0.057 | 0.08 | Ω |
| | | R _{DS} (ON) | V _{GS} = 10 V, I _D = 12 A | _ | 0.036 | 0.046 | |
| Forward transfer | r admittance | Y _{fs} | V _{DS} = 10 V, I _D = 12 A | 10 | 16 | _ | S |
| Input capacitano | e | C _{iss} | | _ | 1000 | _ | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 200 | _ | pF |
| Output capacitance | | Coss | | _ | 550 | _ | |
| Switching time | Rise time | t _r | $V_{GS} = 10V \qquad I_{D} = 12A \\ V_{OUT} \qquad R_{L} = 2.5\Omega \\ V_{DD} = 30V$ | _ | 20 | _ | |
| | Turn-on time | t _{on} | | _ | 30 | _ | - ns |
| | Fall time | t _f | | _ | 55 | _ | |
| | Turn-off time | t _{off} | Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$ | | 130 | _ | |
| Total gate charge (Gate-source plus gate-drain) | | Qg | | _ | 38 | _ | |
| Gate-source charge | | Q _{gs} | $V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$ | | 25 | _ | nC |
| Gate-drain ("miller") charge | | Q _{gd} | | _ | 13 | _ | |

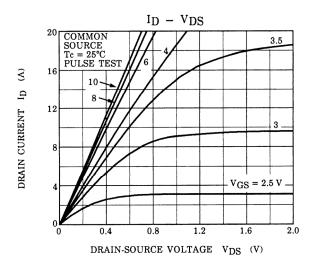
Source-Drain Ratings and Characteristics (Ta = 25°C)

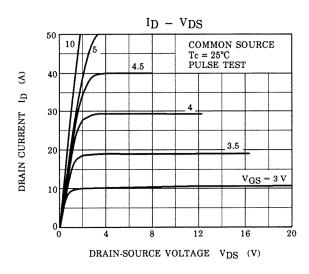
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | _ | _ | 25 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | _ | _ | 100 | Α |
| Forward voltage (diode) | V_{DSF} | I _{DR} = 25 A, V _{GS} = 0 V | _ | _ | -1.8 | V |
| Reverse recovery time | t _{rr} | IDR = 25 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / µs | _ | 50 | _ | ns |
| Reverse recovered charge | Q _{rr} | 1DR = 25 A, VGS = 0 V, αIDR / αt = 50 A / μs | | 35 | _ | μC |

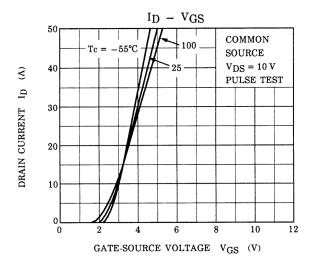
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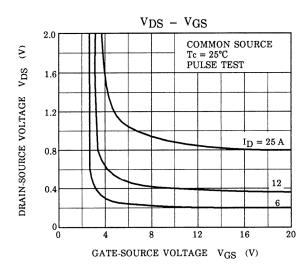


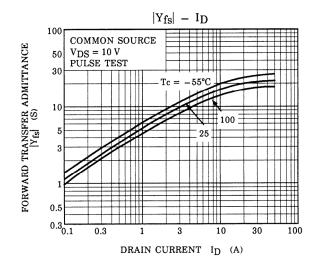
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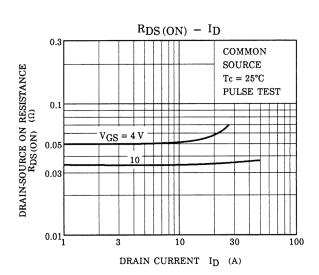


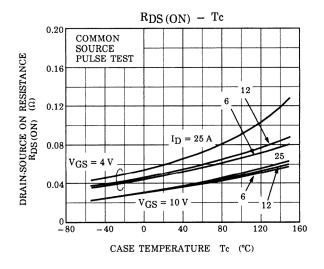


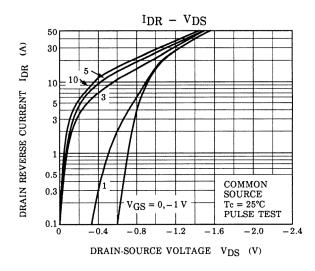


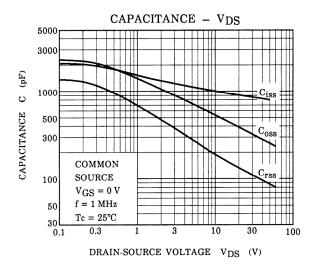


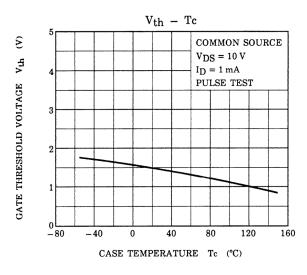


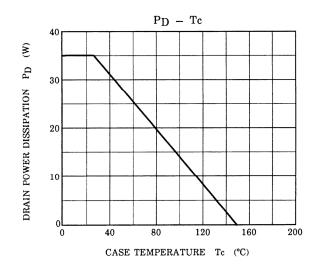


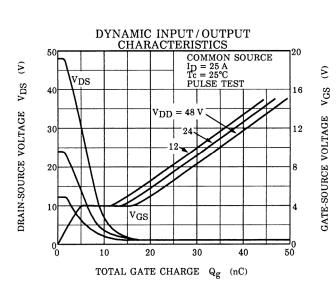


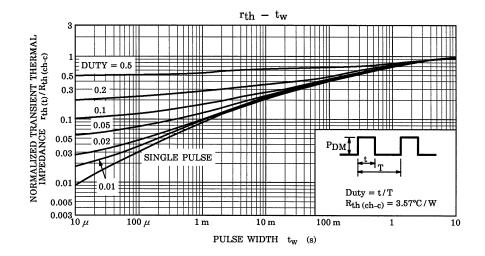


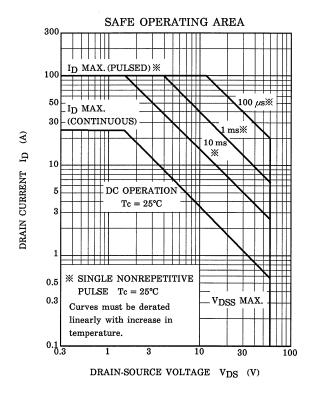


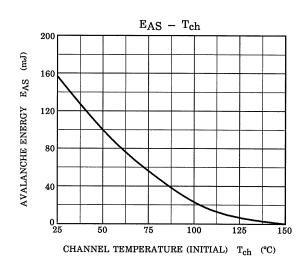


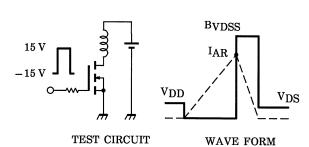












$$R_G = 25 \Omega$$

 $V_{DD} = 25 V$, L = 339 μH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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